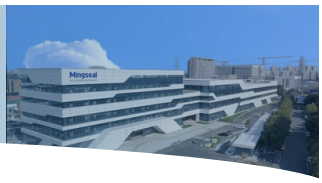


GS600SU GS600SUA Underfill Dispensing Machine for Die Form Underfill FCBGA FCCSP SIP Packaging CUF Application

Our Product Introduction

Basic Information

- Place of Origin: China
- Brand Name: MingSeal
- Certification: ISO CE
- Model Number: GS600SU
- Minimum Order Quantity: 1
- Price: $28000-$150000
- Packaging Details: WOODEN
- Delivery Time: 5-60 days
- Payment Terms: L/C, T/T, D/A, D/P, MoneyGram, Western Union

Product Specification

- Condition: New
- Voltage: 110V/220V
- Automatic Grade: Automatic
- Certification: CE/ISO
- After-sales Service Provided: Engineers Available To Service Machinery Overseas,Online Support,Video Technical Support,Free Spare Parts
- Warranty: 1 Year
- Product Name: Underfill Dispensing Machine
- Highlight: **SMT pcb component placement machine**, **110V pcb component placement machine**, **110V smt placement machine**

Product Description

GS600SU Underfill Dispensing Machine

for Die Form Underfi ll

GS600 SU is a high- speed and high- precision automatic online dispensing system which is developed based on Underfill process requirements of FCBGA/FCCSP.
The system strictly controls the product and adhesive temperature, and intelligently sorts the product operation sequence and the glue replenishment time, reducing the generation of voids and ensuring the operation yield. Meanwhile, it is compatible with international semiconductor communication protocols, and matches the infor- mation management requirements.

■ Application Fields

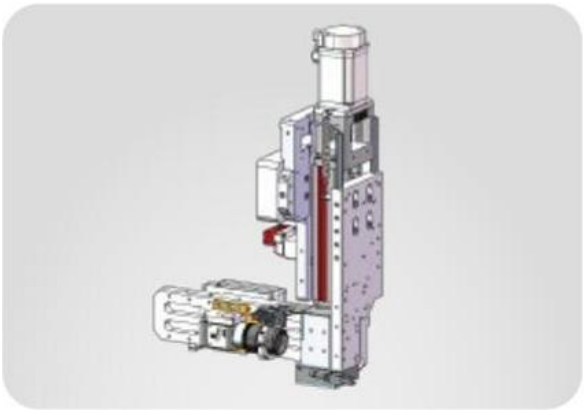
FCBGA Packaging CUF Application FCCSP Packaging CUF Application SiP Packaging CUF Application

■ Technical Specifications

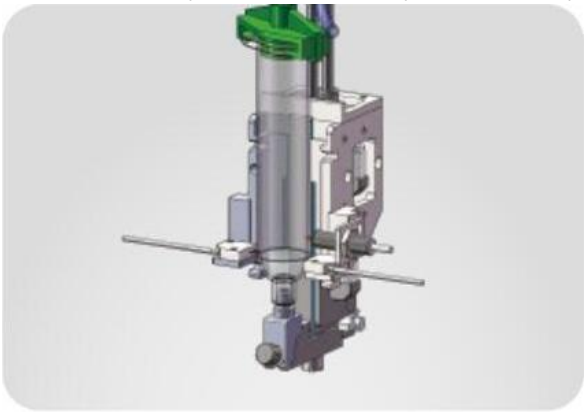
Application Fields	FCBGA, FCCSP, SIP	
Applicable Process	Die Form Underfill	
Cleanliness Level	Cleanliness of working area	Class 100 (Class 1000 workshop) Class 10 (Class 100 workshop)
Transmission Mechanism	Transmission system	X/Y:Linear motor Z: Servo motor&Screw module
	Repeatability (3sigma)	X/Y: ±0.003mm, Z: ±0.005mm
	Positioning accuracy (3sigma)	X/Y: ±0.010mm, Z: ±0.015mm
	Max. movement speed	X/Y: 1000mm/s
		Z: 500mm/s
	Max. accelerated velocity	X/Y: 1g, Z: 0.5g
	Grating resolution	1 μ m
	Z axis movement range(W× D)	3 5 0 mm×4 7 0mm
	Z axis height calibration & compensation Method	Laser sensor (Laser sensor)
	Laser sensor accuracy	2μ m
Dispensing System	Glue control accuracy	± 3 % / 1mg
	Single dot position repeatability CPK 1.0	±25 μ m
	Min. nozzle diameter	30 μ m
	Min. single dot glue weight	0 .001mg/dot
	Max. fluid viscosity	200000cps
	Max. jetting frequency	1000Hz
	Runner/nozzle heating temperature	Room temperature~200℃
	Runner/nozzle heating temp. deviation	± 2 ℃
	Applicable adhesive packaging spec.	5CC/10CC/30CC/50CC/70CC
	Syringe cooling range	Cools down to 15°C below ambient temp.
	Piezo cooling range	Cools down to compressed air source temp.
Track System	Number of tracks	2
	Number of belt sections	One piece
	Max. track transmission speed	300mm/s
	Max. track transmission weight	3kg
	Minimum edge clearance	3 mm
	Track width adjustment range	60mm~ 162mm Adjustable
	Track width adjustment Method	Manual
	Track height	910mm~960mm Adjustable
	Max. thickness of applicable substrate/carrier	6 mm
	Applicable substrate/carrier length range	60mm-325mm
	Vacuum suction pressure Range	-50~-80Kpa Adjustable
	Bottom heating temperature range	Room temperature~180℃
	Bottom heating temp. deviation	≤ ± 1 . 5 ℃
Facilities	Footpri nt W× D× H	2380mm*1550mm*2080mm(Loading&Unloading& display included)
		2380mm*1200mm*2080mm(Loading&Unloading included, display excluded)
	Weight	1600kg
	Power supply	200~240VAC,47~63HZ (Single-phase voltage adaptation power supply)
	Electric current	30A
	Power	6.4KW
	Inhale	(0.5Mpa, 450L/min) ×2

FCBGA Packaging CUF Application
FCCSP Packaging CUF Application
SiP Packaging CUF Application

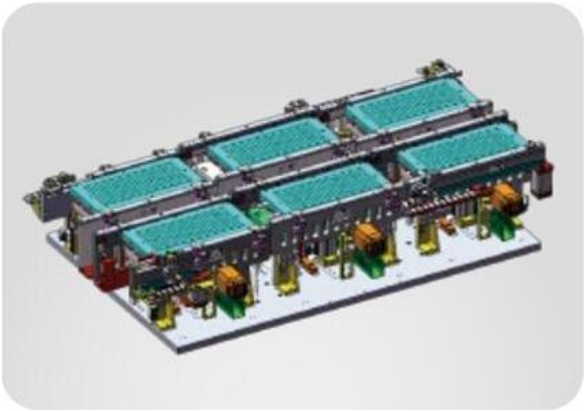
Special Process Modules



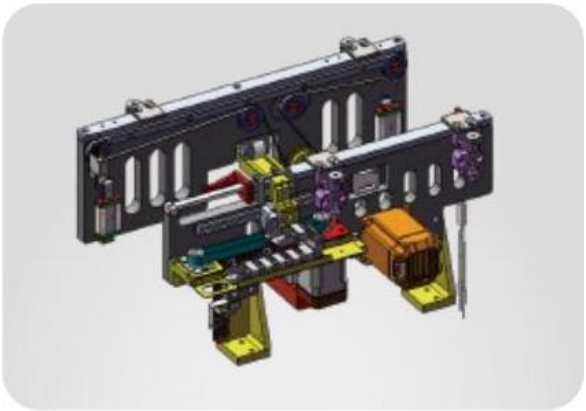
CUF Special Piezoelectric Jetting System
Adhesive insulation + piezoelectric ceramic temperature closed-loop control to avoid system instability caused by temperature influence



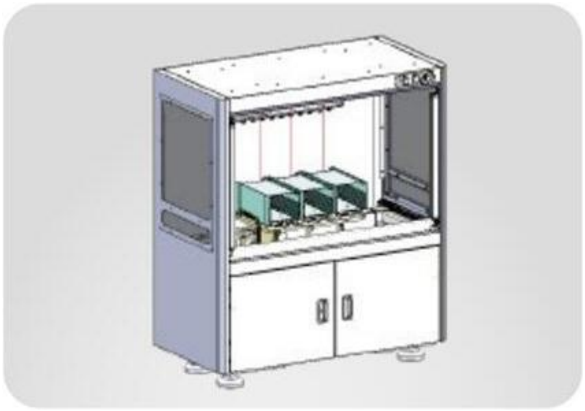
Triple Low-level Alarm
Capacitive detection + magnetic detection + system weighing to avoid poor operation caused by lack of glue



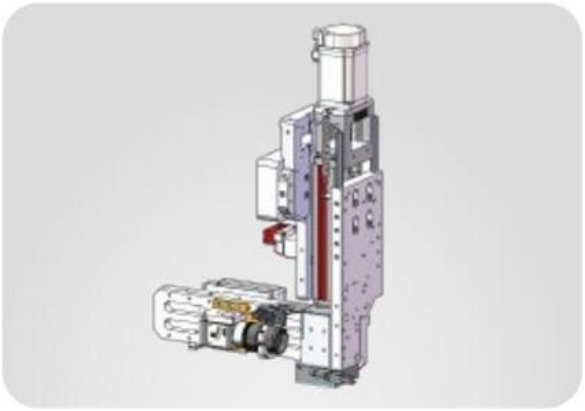
Vacuum Adsorption Heating Fixture
The temperature difference of the whole surface of the fixture is ≤ ±1.5°C, and the temperature is monitored and compensated in real time to avoid poor operation caused by product temperature variation during operation



Press-Down Track
The vacuum adsorption fixture always keeps still, and the track moves up and down to avoid poor operation caused by loss of flatness during reciprocating movement of the vacuum adsorption fixture.



Platform-Type Loading & Unloading System
The feeding sequence is automatically sorted, and the operation is completed within the Plasma time limit
Friendly human-machine interface design



Visual system
Positioning and detection functions
Inspection before operation to avoid defective incoming materials
Inspection after operation to prevent batch defects

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